

MaxTC Power Plus is Mechanical-Device's high performance system.

Designed to handle high power dissipation DUT's, by direct conduction thermal control.



MaxTC Power Plus is designed with high power and flexibility to support a variety of different packages and interfaces.

The system allows for forcing temperature across a wide range of high power device sizes and types, whether socketed or soldered to board.

The Max TC Power Plus unit uses state of the art thermal conduction technology to stimulate DUTs to the desired temperature precisely and consistently by direct contact with a powerful thermal head.

Powerful stand-alone thermal control unit, features:

- Cooling Power -55°C@400W (steady state)
- Ramp Rate up to 75°C/Min
- Temperature stability: ±0.5°C
- Temperature range -75°C to 200°C
- Minor temperature overshooting at high power spikes
- Fast recovery time at high power spikes
- o Replace LN2, Thermostream, Chillers and Chambers
- Remotely controlled via an Ethernet

MaxTC Power Plus is a stand-alone, plug and play Unit, requires only:

- AC input; MaxTC: 208-240 VAC; 1~ 50Hz /60Hz 16A
- Plug type: NEMA L6-20 or 30
- o Cold testing free from condensation

MaxTC Power Plus with a Clip-On and Z axis integrated:

- Robust and small footprint
- Setup is convenient and very fast using clip connections.
- Applies precise and consistent force contact and thermal conductivity.
- Accurate actuating force (Kgf) controlled from a touch screen or remotely
- Simple and quick connection and disconnection of the thermal head
- Adaptable for a variety of soldered and socketed devices
- For full actuation only compressed air supply is required. (80PSI maximum, 4mm air pipe hose)
- Ideal for bench testing, ATE and productive test engineering

System general

Temperature range	-75°C to +200°C
Temperature accuracy	±0.5°C
Typical transition rates	Up to 75°C/min (ramp rate controllable)
Temperature sensor	Type K thermocouple ports, Thermal diode K-type thermocouple
DUT dimensions	Up to 100 mm

Mechanical dimensions

System enclosure mm / inch	(L) 610mm x (W) 505 mm x (H) 365 mm (L) 21.8" x (W) 17.7" x (H) 11.8"
System weight	~65 kg
Thermal head size (WxHxD)	Square type: 73mmx73mmx40mm
Thermal head weight	~1.5kg
Thermal head hose	~2-meter (6.5ft) head distance

Facilities requirements

Electrical	208-240VAC, 50/60Hz, 16A
Operating temp.	10°C to 30°C (non-condensing)
Plug	NEMA L6-20/30
Compressed dry Air *	<.0.5cfm @90psi (-60°C dew point)

Data/Communications

USB	Туре В
Ethernet TCP/IP	RJ-45
Touch screen display	7" LCD

^{*} Compressed Dry Air is required only to avoid condensation during cold testing

Product features

- Fast time to stable temperature(Tcase)
- Short stabilizing soak time and overshooting
- Temperature stability: ±0.5°C
- o Condensation FREE at cold test
- o Maintenance FREE system
- Fully programmable:available drivers LABVIEW, MATLAB, VB, C++, C#,Python and others
- o PID overshooting control
- Stand-alone plug and play system

- o No external chiller or compressed air is required
- Software controlled transition rates to eliminate thermal shock
- Suitable for testing any socketed and soldered DUT up to 100mm size
- o Environmentally friendly operation
- ESD safe product
- o Min and Max temperature safety lock
- o Thermal stream/chamber/chiller replacement
- High reliability testing
- o ATE, SLT and Bench

